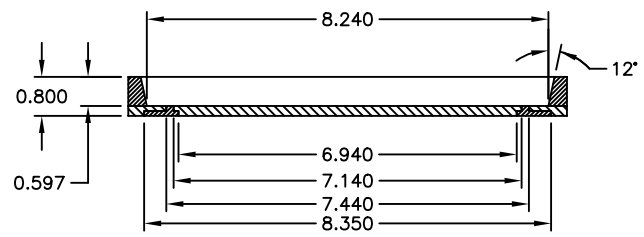
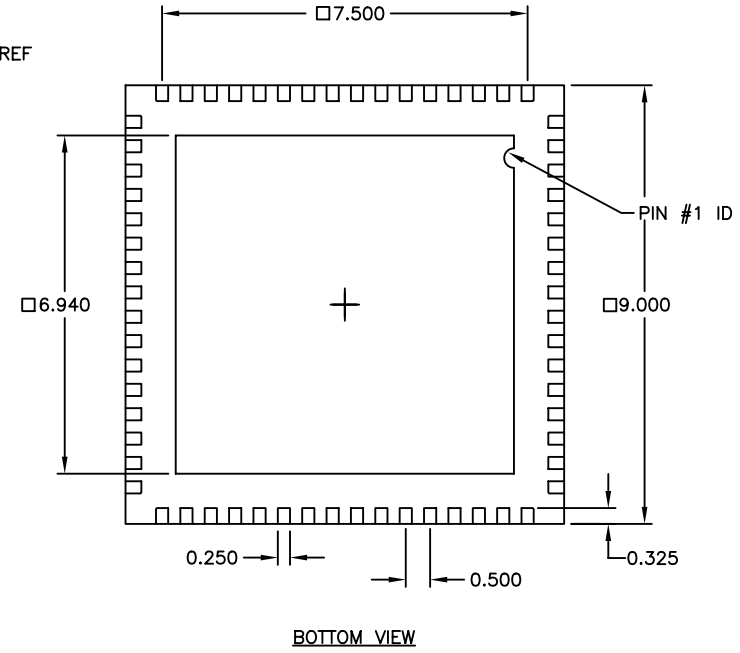
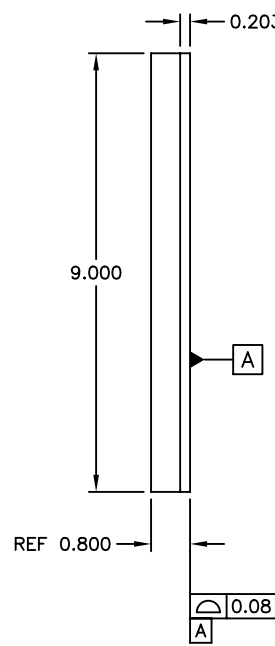
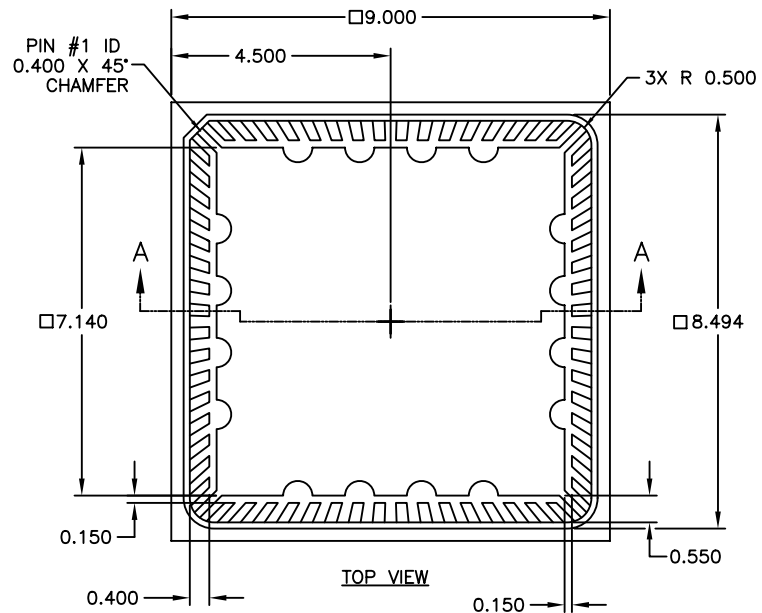


REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
	2/15/11	PRE-PRODUCTION RELEASE	S.SWEN



- NOTES**
- SECTION A-A**
- MATERIALS:**  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
  - FINISH:**  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5µm - 7.6µm) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1µm - 2µm) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
  - PACKAGE MISMATCH:** BODY OFFSET TO LEAD FRAME = 0.076mm MAX
  - UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
  - PACKAGE CONFORMS TO JEDEC MO-220.**

**THIRD ANGLE PROJECTION**

UNLESS OTHERWISE SPECIFIED  
DIMENSIONS ARE IN **MILLIMETER**  
TOLERANCES ARE:  
X.XX ± 0.15 X.XXXX ± ---  
X.XXX ± 0.050 ANGLES: ± 1°

**DO NOT SCALE DRAWING**

<b>DRAWN BY</b>	CAD DEPT.	<b>DATE</b>	4/3/10
<b>APP BY</b>	STEVE S.	<b>DATE</b>	4/3/10
<b>CUSTOMER</b>	---		
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9mm X 9mm  
QFN 64 LEAD 0mPP

<b>SIZE</b>	<b>PART NO.</b>	<b>REV</b>
A	QP-QFN64-9MM-.5MM	B
<b>SCALE</b>	<b>CAD FILE</b>	<b>SHEET 1 OF 1</b>
NONE		